

**METHOD FOR MANUFACTURING DIODE SUBASSEMBLIES USED
IN RECTIFIER ASSEMBLIES OF ENGINE DRIVEN GENERATORS**

Abstract of the Disclosure

A method of manufacturing a diode assembly used in rectifier assemblies of engine-driven generators is disclosed. The diode assemblies have
5 diode cups, semiconductor diode dies and diode leads fitted therein. The diode subassemblies are reflow soldered, such that the semiconductor diode die and diode lead are reflow soldered within a diode cup in an argon/hydrogen atmosphere. In another aspect of the
10 present invention, a lead loader having a removable lead holder that holds diode leads therein is positioned over a diode boat such that the diode leads are aligned with respective diode cups. The lead holder is slid from the lead loader so that the diode
15 leads fall into the center cups which also have the semiconductor die positioned therein. The diode boat is inserted within a furnace for reflow soldering.